

# OKI Semiconductor ML2302

Oki, Network Solutions for a Global Society

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# Recording and Playback LSI with Built-in 2-Bit ADPCM2 Supported FIFO

# **GENERAL DESCRIPTION**

The ML2302 is a recording and playback LSI with built-in FIFO memories for buffering. It employs the new 2-bit ADPCM2 algorithm in addition to conventional 4-bit OKIADPCM and 4-bit OKIADPCM2 algorithms. The ML2302 operates at 2.7 to 3.6 V and supports a variety of applications.

# FEATURES

•

- Built-in two 1024-bit FIFOs (buffering time of 32 ms when using 8 kHz sampling frequency and 4-bit ADPCM)
- Supports five compression algorithms for recording and playback: 2-bit OKIADPCM2; 4/5/6/7-bit OKIADPCM2; 4-bit OKIADPCM; 8/16-bit straight PCM; 8-bit OKI Nonlinear PCM
- Source oscillation frequency 16.384 MHz
  - Sampling frequency (fsam)

4.0 to 12.8 kHz (OKIADPCM2)

4.0 to 25.6 kHz (8-bit straight PCM)

- Supports 8-bit bus interface.
- Built-in voice level detection function (VAC)
- Built-in noise injection function
- Supports external DAC interface.
- Built-in volume control circuit

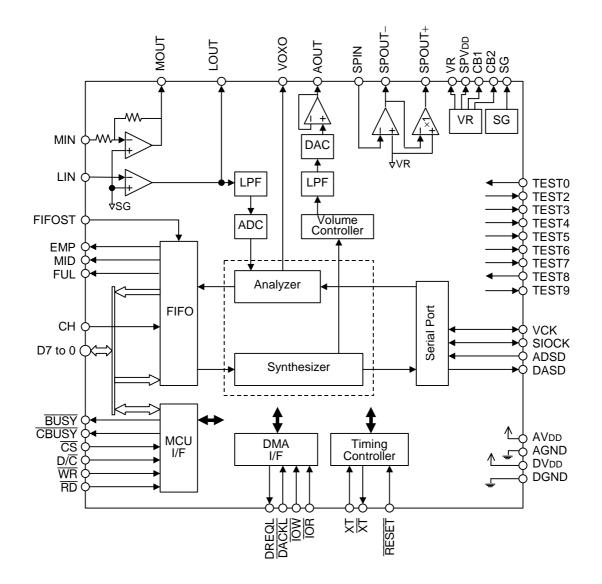
(0 dB to -44 dB: -2 dB step, -44 dB to -80 dB: -4 dB step)

- Built-in 14-bit A/D converter and 14-bit D/A converter
- Built-in low pass filter (LPF)

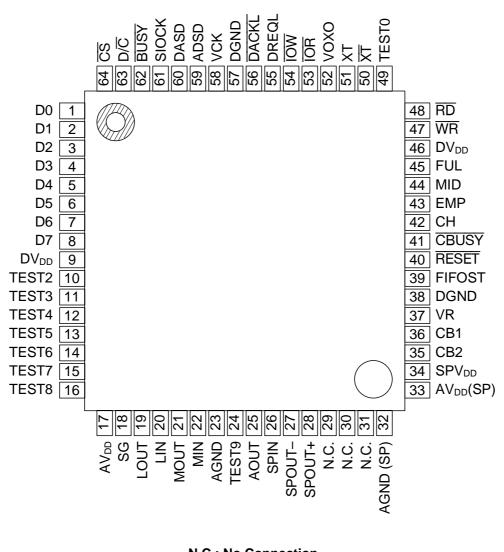
(recording side: analog filter, playback side: digital filter)

- Built-in speaker amplifier (100 mW,  $8\Omega$ )
- Power supply voltage : +2.7 to +3.6 V
- Package : 64-pin plastic TQFP (TQFP64-P-1010-0.50-K) (ML2302TB)
  - : 71-pin W CSP

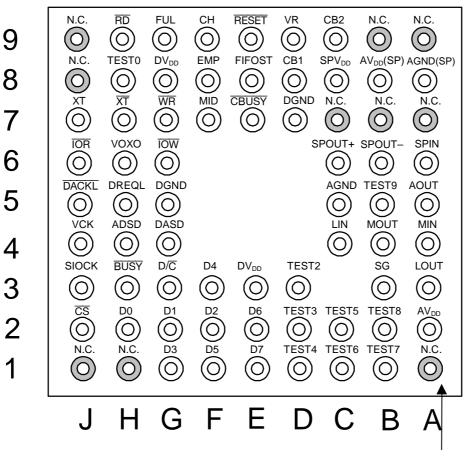
#### **BLOCK DIAGRAM**



**PIN CONFIGURATION (TOP VIEW)** 



N.C.: No Connection 64-pin plastic TQFP



INDEX

71-pin W-CSP (Bottom View)

# **PIN DESCRIPTIONS**

	Pin [QFP)	Symbol	Туре	Description
H2, G2, F2, G1	1 to 8	D7 to 0	I/O	Bidirectional data bus. Command and data inputs from an external microcontroller and memory, and status and data outputs to an external microcontroller and memory.
G7	47	WR	I	Write pulse input pin. This pin pulses "L" when command or voice data is input to D7 to D0 pins.
H9	48	RD	I	Read pulse input pin. This pin pulses "L" when status or voice data is output to D7 to D0.
J2	64	CS	I	Accepts write pulse and read pulse when this pin is "L".
G3	63	D/C	I	Voice data is input or output to and from D7 to D0 when this pin is "H".
H3	62	BUSY	0	This pin outputs a "L" level during RECORDING, PLAYBACK, or PAUSE.
E7	41	CBUSY	0	Accepts a command during this pin is "H".
F8	43	EMP	0	"H" indicates that there is no data in FIFO memory. During playback, voice synthesis starts when EMP changes to "L". Active "H" can be changed to active "L".
F7	44	MID	0	"H" level indicates that there is more than half of the FIFO memory.
G9	45	FUL	0	"H" level indicates that FIFO memory is full of data. During playback, this pin is "H" and data cannot be written in FIFO memory. During recording, data is not written after FIFO memory is full of data. Active "H" can be changed to active "L".
F9	42	СН	I	This pin should be set at a "L" level normally and be set at a "H" level when DMA is used.
H5	55	DREQL	0	When DMA transfer is selected, "H" level DREQL outputs a signal to request a DMA transfer. Active "H" can be changed to active "L".
J5	56	DACKL	I	Input to DACKL a signal when DMA transfer is permitted by the DMA controller. when DACKL is "L", TOW and TOR signals are accepted. Active "L" can be changed to active "H" by command input. If DMA transfer is not used, set this pin to "H" level.
G6	54	ĪOW	I	Write pulse Input pin to write external memory data to ML2302 during DMA transfer. If DMA transfer is not used, set this pin to "H" level.
J6	53	ĪOR	I	Read pulse input pin to read data of ML2302 during DMA transfer. If DMA transfer is not used, set this pin to "H" level.
H4	59	ADSD	I	16-bit serial data input pin when external A/D converter is used. If external A/D converter is not used, set this pin to "L" level.
G4	60	DASD	0	16-bit serial data input pin when external D/A converter is used.

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Pin (WCSP)	Pin (TQFP)	Symbol	Туре	Description
J3	61	SIOCK	I/O	16-bit serial data transfer clock when external A/D or D/A converter is used.
J4	58	VCK	I/O	Outputs sampling frequency selected. Input pin when slave mode is selected.
J7 H7	51 50	XT XT	I O	Oscillator connection pins. when external clock is used, input clock into XT pin and leave $\overline{\text{XT}}$ pin open. Oscillation stops during reset or power down mode. Figure (a) shows Oscillation Equivalent Circuit.
E9	40	RESET	I	When this pin is "L", the LSI is initialized and AOUT is set to the GND level.
E8	39	FIFOST	I	When this pin is "L", EMP, MID, and FULL of playback FIFO can be monitored. When this pin is "H", EMP, MID, and FULL of record FIFO can be monitored.
B3	18	SG	0	Analog circuit signal ground pin. This pin is connected to GND during reset or power down mode.
A4 C4	22 20	MIN LIN	I	Inverting input pin for built-in OP amplifier. Non-inverting input pin is connected to SG (Signal Ground).
B4 A3	21 19	MOUT LOUT	0	MOUT is the output of internal OP amplifier to MIN, and LOUT is to LIN.
A5	25	AOUT	0	This is the output of the analog playback waveform.
H6	52	VOXO	0	Voice level detection signal
H8, B2	49, 16	TEST0, 8	1	Pins for testing. Set the pins to "L".
E3, G8	9, 46	DV <sub>DD</sub>	_	Digital power supply pin. Insert a minimum 0.1 $\mu$ F bypass capacitor between this pin and DGND pin
D7, G5	38, 57	DGND	_	Digital GND pin.
A2, B8	17, 33	AV <sub>DD</sub>	_	Analog power supply pin. Insert a minimum 0.1 $\mu$ F bypass capacitor between this pin and AGND pin.
C5, A8	23, 32	AGND	—	Analog GND pin.
C9, D8	36 35	CB1 CB2	0	This pin is used to connect a capacitor for voltage multiplier power supply. Insert a 1 $\mu$ F capacitor between CB1 and CB2.
C8	34	SPV <sub>DD</sub>	0	Voltage multiplier power supply output pin for speaker amplifier. Connect a 1 $\mu$ F capacitor to this pin in order to stabilize the speaker amplifier circuit.
D9	37	VR	0	Bias output pin for speaker amplifier. Set this pin to the GND level during reset or power down mode.
A6	26	SPIN	I	Voice signal input pin for speaker amplifier.
B6	27	SPOUT-	0	Speaker amplifier output pin. This pin outputs a signal in reverse phase to the signal that is input to the SPIN pin.
C6	28	SPOUT+	0	Speaker amplifier output pin. This pin outputs a signal in phase to the signal that is input to the SPIN pin.
D1, D2, D3, C1, C2, B1, B5	10~15 ,24	TEST2 to 7, 9	0	Pins for testing. Leave these pins open.

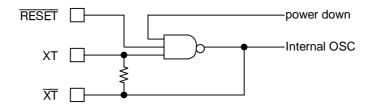


Figure (a) Oscillation Equivalent Circuit

# ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V <sub>DD</sub>		-0.3 to +7.0	V
Input Voltage	V <sub>IN</sub>	Ta = 25°C	-0.3 to V <sub>DD</sub> +0.3	V
Maximum Power Dissipation	PD		689.6	mW
Temperature Storage	T <sub>STG</sub>	—	-55 to +150	°C

# **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V <sub>DD</sub>	DGND = AGND = 0 V	+2.7 to +3.6	V
Operating Temperature	T <sub>Op</sub>	—	-10 to +70	°C
Master Clock Frequency	fosc	_	16.384	MHz
Speaker Amplifier Load Impedance	R <sub>LSP</sub>	—	8 to ∞	Ω

# **ELECTRICAL CHARACTERISTICS**

# **DC Characteristics**

		$(DV_{DD} = AV_{DD} = 2.7 \text{ to } 3.6)$	6 V, DGND = /	AGND = 0 V, T	Ta = -10 to +7	0°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
High-level Input Voltage	V <sub>IH</sub>	_	$0.85 \times V_{\text{DD}}$		—	V
Low-level Input Voltage	V <sub>IL</sub>	_			$0.15\times V_{\text{DD}}$	V
High-level Output Voltage (*1, *5)	V <sub>OH1</sub>	L	V <sub>DD</sub> – 0.3		—	V
High-level Output Voltage (*2, *5)	V <sub>OH2</sub>	I <sub>OH</sub> = −40 μA	$V_{\text{DD}} - 0.3$		—	V
Low-level Output Voltage (*1, *5)	V <sub>OL1</sub>	I <sub>OL</sub> = 2 mA			0.45	V
Low-level Output Voltage (*2, *5)	V <sub>OL2</sub>	$I_{OL} = 2 IIIA$	_	_	0.8	V
High-level Input Current (*3)	I <sub>IH1</sub>		_	_	10	μA
High-level Input Current (*4)	I <sub>IH2</sub>	$V_{IH} = V_{DD}$	1		7	μA
Low-level Input Current (*3)	I <sub>IL1</sub>	Vıı = GND	-10	_	—	μA
Low-level Input Current (*4)	I <sub>IL2</sub>		-7		-1	μA
Operating Current Consumption	I <sub>DD</sub>	$f_{osc} = 16$ MHz, without load		15	20	mA
Standby Current		At reset, without load Ta = −10 to +50°C	_	_	10	μA
Consumption	I <sub>DDS</sub>	At reset, without load Ta = +50 to +70°C	—	_	50	μA

\*1 : Applied to input pins excluding  $\overline{XT}$  pin.

\*2 : Applied to XT pin.
\*3 : Applied to output pins excluding XT pin.
\*4 : Applied to XT pin.
\*5 : If an output pin is shortcircuited to V<sub>DD</sub> or GND, the LSI may be damaged.

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# **Analog Characteristics**

		$(DV_{DD} = AV_{DD} = 2.7 \text{ to } 3.6 \text{ V},$	DGND = A	GND = 0 V,	Ta = −10 to	• +70°C)
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
D/A Output Relative Error	V <sub>DAE</sub>	Without load	_	_	40	mV
LOUT Allowable Voltage Range	V <sub>LOUT</sub>	$V_{DD} = 3 V$	0.75	—	2.25	V
OP Amplifier Open Loop Gain	G <sub>OP</sub>	$f_{in} = 0$ to 4 kHz	40	_	_	dB
DAC Output Impedance	R <sub>DAO</sub>	DAC output is selected AOUT = 1/2V <sub>DD</sub>	30	50	70	kΩ
OP Amplifier Input Impedance	R <sub>INA</sub>	(Excluding MIC amplifier)	1	_	_	MΩ
MIC Amplifier Input Impedance	R <sub>INAM</sub>	MIC amplifier	8.1	11.6	15.1	kΩ
MOUT, LOUT Load Resistance	Routa	_	50	—	—	kΩ
AOUT Load Resistance	R <sub>AOL</sub>	—	50	_	_	kΩ
VR Output Voltage	V <sub>VR</sub>	—	1.22	1.25	1.28	V
SG Output Voltage	$V_{SG}$	$V_{DD} = 3.0 V$	1.47	1.5	1.53	V
SPIN Input Impedance	R <sub>ISP</sub>		1	_	_	MΩ
Voltage Gain	AV1	$\begin{array}{l} {\sf SPIN} \rightarrow {\sf SPOUT-} \\ ({\sf Loop\ resistor\ is\ not\ connected}) \\ {\sf f}_{\sf IN} = 10\ {\sf kHz} \end{array}$	40	_	_	dB
	AV2	$SPOUT- \to SPOUT+$	-0.4	0	0.4	dB
Differential Output Power	PD1	$\label{eq:VDD} \begin{array}{l} V_{DD} = 3.0 \ V \\ RL = 8\Omega \\ THD \geq 10\% \end{array}$	100	_	—	mW
SPOUT+/– Output Voltage	$V_{SP}$	No signal is input.	1.17	1.25	1.33	V
SPOUT+/- Output Offset Voltage	V <sub>SPOF</sub>	No signal is input.	_		±50	mV
SPOUT+/– Output "H" Voltage	V <sub>SPH</sub>	I <sub>OH</sub> = +10 mA	2.2		_	V
SPOUT+/– Output "L" Voltage	$V_{SPL}$	I <sub>OL</sub> = -10 mA	—	—	0.25	V

#### **FUNCTIONAL DESCRIPTION**

# **Voice Synthesis Algorithms**

The ML2302 supports five PCM algorithms to process various kinds of voices.

- 1. 4-bit OKIADPCM algorithm
- 2. 4/5/6/7/8-bit OKIADPCM2 algorithm
- 3. 2-bit OKIADPCM algorithm
- 4. 8/16-bit straight PCM algorithm
- 5. 8-bit OKI Non-linear PCM algorithm

Voice Synthesis Algorithms and Sampling Frequencies during Recording and Playback

The relationships between the voice synthesis algorithms and sampling frequencies available during recording and playback are shown in Tables 1.1.1 and 1.1.2.

Table 1.1.1 During Recording

f <sub>sam</sub> (kHz)														
Voice	4.0	5.3	6.1	6.4	8.0	9.8	10.7	11.6	12.8	14.2	16.0	18.3	21.3	25.6
synthesis algorithm														
4-bitADPCM	0	0	0	0	0	0	0	0	0	×	×	×	×	×
4/5/6/7/8-bitADPCM2	0	0	0	0	0	0	0	0	0	×	×	×	×	×
2-bitADPCM2	0	0	0	0	0	0	0	0	0	×	×	×	×	×
8-bit straight PCM	0	0	0	0	0	0	0	0	0	0	0	0	0	0
16-bit straight PCM	0	0	0	0	0	0	0	0	0	0	0	0	×	×
8-bit Non-linear PCM	×	×	×	×	×	×	×	×	×	×	×	×	×	×

#### Table 1.1.2 During Playback

f <sub>sam</sub> (kHz)														
Voice	4.0	5.3	6.1	6.4	8.0	9.8	10.7	11.6	12.8	14.2	16.0	18.3	21.3	25.6
synthesis algorithm														
4-bitADPCM	0	0	0	0	0	0	0	0	0	×	×	×	×	×
4/5/6/7/8-bitADPCM2	0	0	0	0	0	0	0	0	0	×	×	×	×	×
2-bitADPCM	0	0	0	0	0	0	0	0	0	×	×	×	×	×
8-bit straight PCM	0	0	0	0	0	0	0	0	0	0	0	0	0	0
16-bit straight PCM	0	0	0	0	0	0	0	0	0	0	0	0	×	×
8-bit Non-linear PCM	0	0	0	0	0	0	0	0	0	0	0	0	×	×

#### **Data Configuration**

The data configuration of each voice synthesis algorithm is shown in Tables 1.2.1 to 1.2.7.

Table 1.2.1 2-bitADPCM2 Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
MSB1	LSB1	MSB2	LSB2	MSB3	LSB3	MSB4	LSB4

# Table 1.2.2 4-bitADPCM Algorithm, 4-bit ADPCM2 Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
MSB1	3SB1	2SB1	LSB1	MSB2	3SB2	2SB2	LSB2

#### Table 1.2.3 5-bitADPCM2 Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
×	х	х	MSB1	4SB1	3SB1	2SB1	LSB1

# Table 1.2.4 6-bitADPCM2 Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
×	×	MSB1	5SB1	4SB1	3SB1	2SB1	LSB1

#### Table 1.2.5 7-bitADPCM2 Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
×	MSB1	6SB1	5SB1	4SB1	3SB1	2SB1	LSB1

# Table 1.2.6 8-bit ADPCM2 Algorithm, 8-bit Non-linear PCM Algorithm, 8-bit straight PCM Algorithm

D7	D6	D5	D4	D3	D2	D1	D0
MSB1	7SB1	6SB1	5SB1	4SB1	3SB1	2SB1	LSB1

#### Table 1.2.7 16-bit straight PCM Algorithm

D7	D6	D5	D4	D3	D2	D1	D0	_
MSB1	15SB1	14SB1	13SB1	12SB1	11SB1	10SB1	9SB1	(first)
8SB1	7SB1	6SB1	5SB1	4SB1	3SB1	2SB1	LSB1	(second)
							×:	Don't care

#### **FIFO Memory Configuration**

The ML2302 has two FIFO memories; one is for recording and other is for playback.

The configuration of FIFO memory can be changed with a command. Select a FIFO configuration considering buffering times.

Initially, FIFO memory for recording and FIFO memory for playback each is provided with 1024 bits (128 words  $\times$  8 bits).

ML2302 cannot command recording and playback at the same time.

1. Combination of FIFO memory capacities

Table 1.3.1 shows the combination of FIFO memory capacities in recording and playback modes.

Mode	Recording	Playback	-
1024 bits	128 w $\times$ 8 bits	128 w $\times$ 8 bits	*Initial value
512 bits	$64 \text{ w} \times 8 \text{ bits}$	$64 \text{ w} \times 8 \text{ bits}$	_
256 bits	$32 \text{ w} \times 8 \text{ bits}$	32 w $\times$ 8 bits	-

#### Table 1.3.1

2. Voice synthesis algorithms and maximum buffering times

Table 1.3.2 shows the maximum buffering times when the FIFO capacity is 1024 bits and the sampling frequency is 8 kHz.

#### Table 1.3.2

Mode		
Voice	Recording	Playback
synthesis algorithm		
4-bit OKIADPCM	32 ms	32 ms
4-bit OKIADPCM2	32 ms	32 ms
5/6/7/8-bit OKIADPCM2	16 ms	16 ms
2-bit OKIADPCM2	64 ms	64 ms
8-bit straight PCM	16 ms	16 ms
16-bit straight PCM	8 ms	8 ms
8-bit OKI Non-linear PCM	Note)	16 ms

Note: The 8-bit OKI Non-linear PCM algorithm cannot be used during recording.

# **COMMAND LIST**

	1	1	1	1	1	1	1	
D7	D6	D5	D4	D3	D2	D1	D0	Function
0	0	0	0	W3	W2	0	0	POWER DOWN
0	0	0	1	Х	Х	Х	Х	Disable
0	0	1	0	S3	S2	S1	S0	Sets sampling frequency.
0	0	1	1	C3	C2	C1	C0	RECORDING, PLAYBACK, STOP, PAUSE
0	1	0	0	VH3	VH2	VH1	VH0	Volume control 1
0	1	0	1	VL3	VL2	VL1	VL0	Volume control 2
0	1	1	0	0	K2	K1	K0	Level detection, noise injection
0	1	1	1	P3	P2	P1	P0	Voice synthesis algorithm
1	0	0	0	R3	R2	R1	0	Analog specification 1
1	0	0	1	A3	A2	A1	0	Analog specification 2
1	0	1	0	0	B2	B1	B0	FIFO memory byte configuration
1	0	1	1	F3	F2	F1	0	Signal output format
1	1	0	0	G3	G2	G1	G0	DMA Transfer
1	1	0	1	13	0	J1	JO	Serial port
1	1	1	0	112	U2	U1	110	Fast Forward/Rewind setting 1 (quick speaking/slow
			U	U3 U2 U1 U0		00	speaking)	
1	1	1	1	Y3	Y2	Y1	Y0	Fast Forward/Rewind setting 2

# Table 2.1

#### **READING STATUS**

The ML2302 supports the following seven status flags.

# Table 4.1

Pin	Status	Description
D7	Data Recording/Playing flag	High when recording or playback is in progress
D6	Don't Care	
D5	Pause flag	High when playback of left voice is paused
D4	Don't Care	
D3	EMP Information Output flag	Output the same signal as the EMP pin. Note)
D2	MID Information flag	Output the same signal as the MID pin. Note)
D1	FUL Information flag	Output the same signal as the FUL pin. Note)
D0	Data Transfer Error flag	See "Data Transfer Errors".

Note: EM, MID, and FUL are either at the active "H" or at the active "L" by setting the signal output format by the command. The status signals on D3 to D1 are determined depending on the status of the FIFOST pin as shown below.

	FIFOST = "0"	FIFOST = "1"
D3	EMP signal for playback FIFO	EMP signal for recording FIFO
D2	MID signal for playback FIFO	MID signal for recording FIFO
D1	FUL signal for playback FIFO	FUL signal for recording FIFO

# **Data Transfer Errors**

The Data Transfer flag supports the following four errors.

- (1) "H" when data is read while EMP for recording FIFO is "H"
- (2) "H" when data is written while FUL for playback FIFO is "H"
- (3) "H" when a command is written while CBUSY is "L".
- (4) "H" when recording data cannot be written in FIFO while FUL for recording FIFO is "H".

\*These four errors are released when a normal transfer described below is carried out.

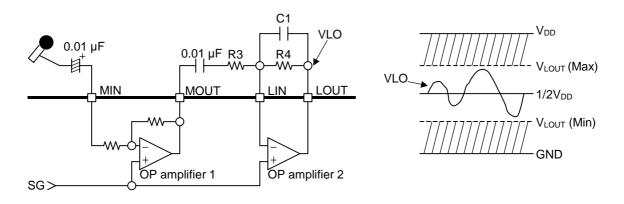
- (1) Reads data while EMP for recording FIFO is "L".
- (2) Writes data while FUL for playback FIFO is "L".
- (3) Writes a command while CBUSY is "H".
- (4) The error flag is released when data is written in recording FIFO within LSI after reading data from recording FIFO and setting FUL for recording FIFO to "L".

#### ANALOG INPUT AMPLIFIER CIRCUIT

The ML2302 contains two OP amplifiers to amplify a voice signal from a microphone. Each OP amplifier is provided with the inverting input pin and output pin.

The analog circuit reference voltage SG (signal ground) is input internally to the non-inverting input of each amplifier.

For amplification, form an inverting amplifier circuit and adjust the amplification ratio by using external resistors.



#### Figure 6.1

The constants of R4 and C1 are determined by  $f = 1/2\pi R \cdot C$ . C1 is 39.89 pF  $\cong$  39 pF when R4 is 200 k $\Omega$ , where the cut-off frequency of LPF is f = 20 kHz.

During recording, the output VLO of the OP amplifier is input to LPF.

Adjust the amplification ratio by an external resistor so that the output voltage  $V_{LOUT}$  may be in the LOUT-permissible input voltage range.

If  $V_{LOUT}$  is not in this range, the waveform of the LPF output may be deformed.

Table 6.1 shows an examples of LOUT-permissible input voltage ranges of the ML2302.

#### Table 6.1

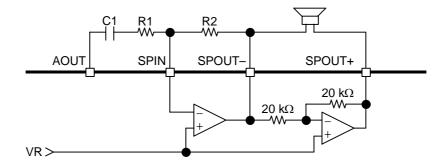
Model name	Supply voltage V <sub>DD</sub>	LOUT-permissible v	LOUT-permissible range	
		MIN	MAX	LOOT-permissible range
ML2302	3 V	0.75 V	2.25 V	1.5 V <sub>pp</sub>

The load resistance  $R_{OUTA}$  of the OP amplifier is 50 k $\Omega$ . Therefore, the feedback resistors R4 and R3 of the amplifying circuit must be 50 k $\Omega$  or higher.

#### **SPEAKER DRIVING AMPLIFIER**

The ML2302 contains two OP amplifiers for driving a speaker; SPOUT– which is the inverting type output for a voice multiplication signal SPIN and SPOUT+ which is the non-inverting type output.

Though SPOUT+ alone can be used, when differential outputs are used, it is possible to gain not only an amplitude two times that of when a single OP amplifier is used but also a good volume even if a low power supply voltage is used. The connection diagram of differential outputs are shown below.



Note 1: The gain of a speaker amplifier is determined by R1 and R2.

V (SPOUT-) = 
$$-\frac{R2}{R1} \cdot V(SPIN)$$
  
V (SPOUT+) =  $-V(SPOUT-) = \frac{R2}{R1} \cdot V(SPIN)$ 

Note 2: C1 is an AC coupling capacitance. The cut-off frequency at a low field is determined by the following equation. Select a value of C1 in accordance with a pass band.

 $f_c = \frac{1}{2 \times \pi \times C1 \times R1} (Hz)$ 

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#### **RECORDING TIME AND MEMORY CAPACITY**

The recording time of the ML2302 is dependent on the storage capacitance of external memory, the sampling frequency, and the width of ADPCM bits that have been specified. The recording time of the ML2302 is expressed by

Recording time =  $\frac{\text{Memory size (in kbits)}}{\text{Sampling frequency (kHz) × Width of ADPCM bits}} \times \frac{4080}{4096}$ 

For example, when 8.0 kHz of sampling frequency, 4 bits of ADPCM2, and 8 Mbits of memory size are set, the recording time is calculated below.

Recording time =  $\frac{8000}{8.0 \times 4} \times \frac{4080}{4096}$  = 249 seconds = 4 minutes 9 seconds

### **CONNECTION OF POWER SUPPLY**

The ML2302 contains a single power supply as shown in Figure 7.1. The power supply is connected to the analog unit and digital unit separately.

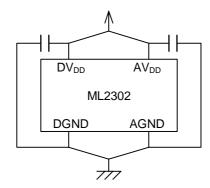


Figure 7.1

Avoid following power supply connections.

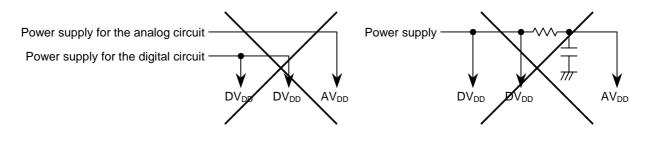
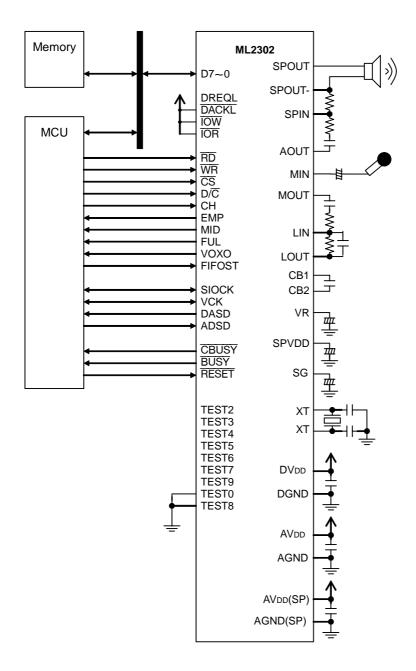
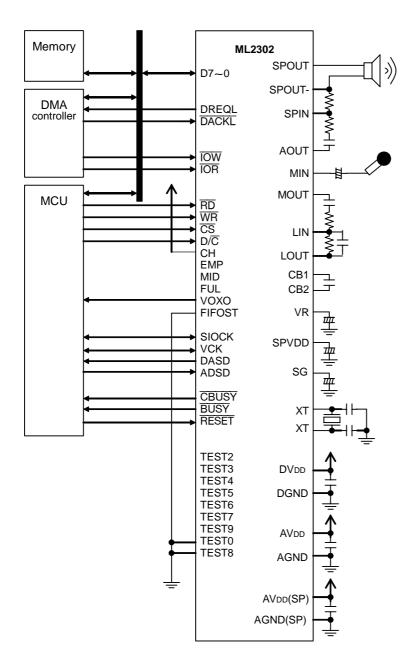


Figure 7.2

# **APPLICATION CIRCUIT EXAMPLE**

(1) MCU and External Interface

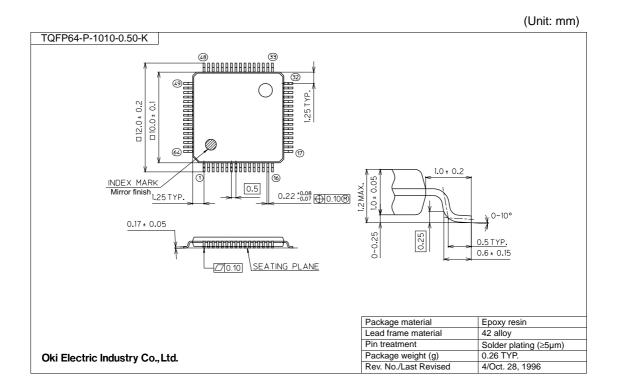




(2) Interface when DMA controller is Used

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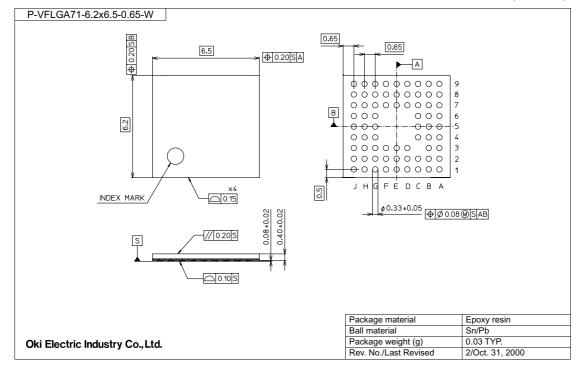
# PACKAGE DIMENSIONS



Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

#### (Unit: mm)



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# **REVISION HISTORY**

Document		Pa	ge			
No.	Date	Previous	Current	Description		
		Edition	Edition			
FEDL2302DIGEST-01	Apr. 2001	_	_	Final edition 1		
FEDL2302DIGEST-02	Apr. 3, 2003	-	-	Final edition 2		
FEDL2302DIGEST-03	May 30, 2003	-	-	Final edition 3		
	Jan. 20, 2004	1	1	Partially changed contents of the "FEATURES" section.		
FEDL2302DIGEST-04		2	2	Modified the block diagram.		
		-	10-18	Added pages.		
FEDL2302DIGEST-05	Dec. 27, 2004	6	6	Partially corrected the Pin Descriptions.		
FEDE2302DIGE31-05	Dec. 27, 2004	19	19,20	Modified the application circuit example.		

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